

PATENT ASSIGNMENT

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NATURE OF CONVEYANCE:		ASSIGNMENT OF ASSIGNOR'S INTEREST			
CONVEYING PARTY DATA					
Name		Execution Date			
Shien Chun Tseng		2004-02-17			
RECEIVING PARTY DATA					
Name	Street Address	Internal Address	City	State/Country	Postal Code
Powerchip Semiconductor Corp.	No. 12, Li-Hsin Rd. I, Science-based Industrial	Park	Hsin-Chu City	TAIWAN	
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DATE SIGNED:		2004-06-27			
Total Attachments: 1 source=LKSP0036_0_A1ASS1.tif					

CH \$40.00 503105 10710237

ASSIGNMENT OF INVENTION

I, (Assignor Name) Shien Chun Tseng, residing at (Address)
No. 12, Lane 54, Wu-Feng St., Chu-Dong Town, Hsin-Chu Hsien, Taiwan, R.O.C.
, have invented a device called

**"METHOD FOR FABRICATING A THROUGH HOLE ON A
SEMICONDUCTOR SUBSTRATE"**

(Assignee name) Powerchip Semiconductor Corp.
(hereinafter 'Assignee'), of (Assignee address)
No. 12, Li-Hsin Rd. I, Science-based Industrial Park, Hsin-Chu City, Taiwan, R.O.C.

wishes to acquire the entire right, title, and interest in and to the invention and to any letters patent that may be granted therefor in the United States and in any and all foreign countries.

Accordingly, in consideration of the sum of One Dollar, (\$1.00) to me in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, Assignor, hereby sells, assigns, and transfers to Assignee the full and exclusive right to the above described invention in the United States and its territorial possessions, and in all foreign countries. The rights granted include the entire right, title, and interest in and to any and all letters patent which may be granted on the invention, including any rights gained by divisions, reissues, continuations, and extensions of the above described application.

I hereby authorize and request the Patent and Trademark Office Officials in the United States and any and all foreign countries to issue any and all letters patent, when issued, to Assignee, as the assignee of my entire right, title, and interest in and to the invention, for the sole use and enjoyment of Assignee and its successors and assignees.

Further, I agree that I will communicate to Assignee or its representatives any facts known to me respecting the invention, to testify in any legal proceedings, to sign all lawful papers, to execute all divisions, continuations, substitutions, renewal and reissue applications, and to generally do those things necessary to aid Assignee and its successors and assigns to obtain and enforce proper protection for the invention in the United States and in any and all foreign countries.

Date: 2004 7. 17, Shien Chun Tseng (Assignor signature)
(請務必簽日期)

Shien Chun Tseng (Print Assignor's name)